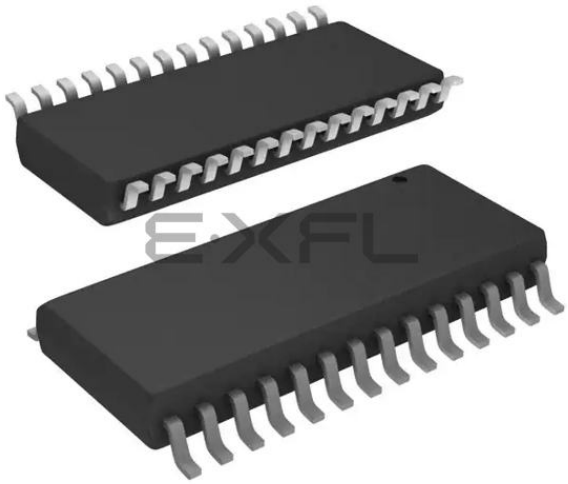
Microchip Technology - PIC16LF1903-I/SO Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1903-i-so

PIC16LF1902/3 Family Types

Device	Data Sheet Index	Program Memory Flash (words)	Data SRAM (bytes)	High-Endurance Flash (bytes)	I/Os(2)	10-bit ADC (ch)	Timers (8/16-bit)	EUSART	LCD			Debug(1)	XLP
									Common Pins	Segment Pins	Total Segments		
PIC16LF1902	(1)	2048	128	128	25	11	1/1	—	4	19	72(3)	H	Y
PIC16LF1903	(1)	4096	256	128	25	11	1/1	—	4	19	72(3)	H	Y
PIC16LF1904	(2)	4096	256	128	36	14	1/1	1	4	29	116	I/H	Y
PIC16LF1906	(2)	8192	512	128	25	11	1/1	1	4	19	72(3)	I/H	Y
PIC16LF1907	(2)	8192	512	128	36	14	1/1	1	4	29	116	I/H	Y

Note 1: I - Debugging, Integrated on Chip; H - Debugging, available using Debug Header.

2: One pin is input-only.

3: COM3 and SEG15 share a pin, so the total segments are limited to 72 for 28-pin devices.

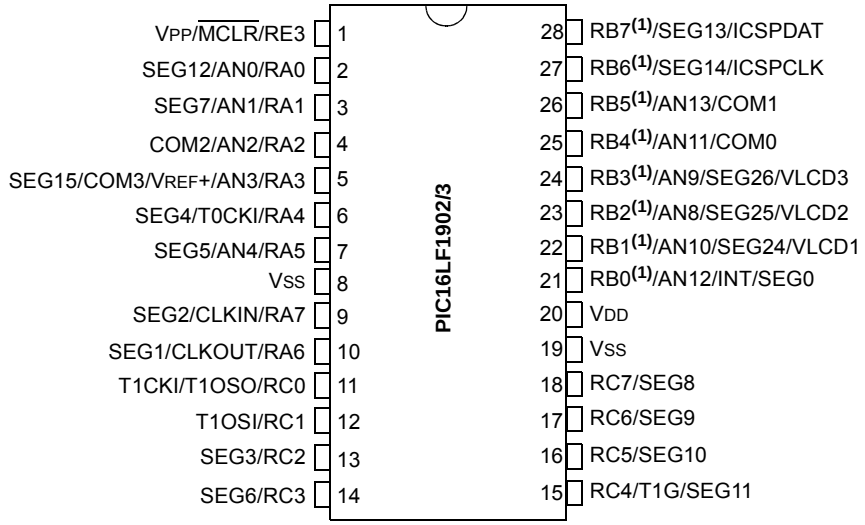
Data Sheet Index: (Unshaded devices are described in this document.)

1: DS40001455 PIC16LF1902/1903 Data Sheet, 28-Pin Flash, 8-bit Microcontrollers.

2: DS40001569 PIC16LF1904/6/7 Data Sheet, 28/40/44-Pin Flash, 8-bit Microcontrollers.

Pin Diagrams

FIGURE 1: 28-PIN PDIP, SOIC, SSOP



Note 1: These pins have interrupt-on-change functionality.

REGISTER 4-2: CONFIGURATION WORD 2

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
LVP(1)	$\overline{\text{DEBUG}}$(2)	$\overline{\text{LPBOR}}$	BORV(3)	STVREN	—
bit 13					bit 8

U-1	U-1	U-1	U-1	U-1	U-1	R/P-1	R/P-1
—	—	—	—	—	—	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit(1)
1 = Low-voltage programming enabled
0 = High-voltage on $\overline{\text{MCLR}}$ must be used for programming

bit 12 **$\overline{\text{DEBUG}}$:** In-Circuit Debugger Mode bit(2)
1 = In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
0 = In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger

bit 11 **$\overline{\text{LPBOR}}$:** Low-Power BOR bit
1 = Low-Power BOR is disabled
0 = Low-Power BOR is enabled

bit 10 **BORV:** Brown-out Reset Voltage Selection bit(3)
1 = Brown-out Reset voltage (V_{BOR}), low trip point selected
0 = Brown-out Reset voltage (V_{BOR}) high trip point selected

bit 9 **STVREN:** Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 8-2 **Unimplemented:** Read as '1'

bit 1-0 **WRT<1:0>:** Flash Memory Self-Write Protection bits
2 kW Flash memory (PIC16LF1902 only):
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to 7FFh may be modified by PMCON control
01 = 000h to 3FFh write-protected, 400h to 7FFh may be modified by PMCON control
00 = 000h to 7FFh write-protected, no addresses may be modified by PMCON control
4 kW Flash memory (PIC16LF1903 only):
11 = Write protection off
10 = 000h to 1FFh write-protected, 200h to FFFh may be modified by PMCON control
01 = 000h to 7FFh write-protected, 800h to FFFh may be modified by PMCON control
00 = 000h to FFFh write-protected, no addresses may be modified by PMCON control

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.
2: The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.
3: See V_{BOR} parameter for specific trip point voltages.

FIGURE 6-4: INTERNAL OSCILLATOR SWITCH TIMING

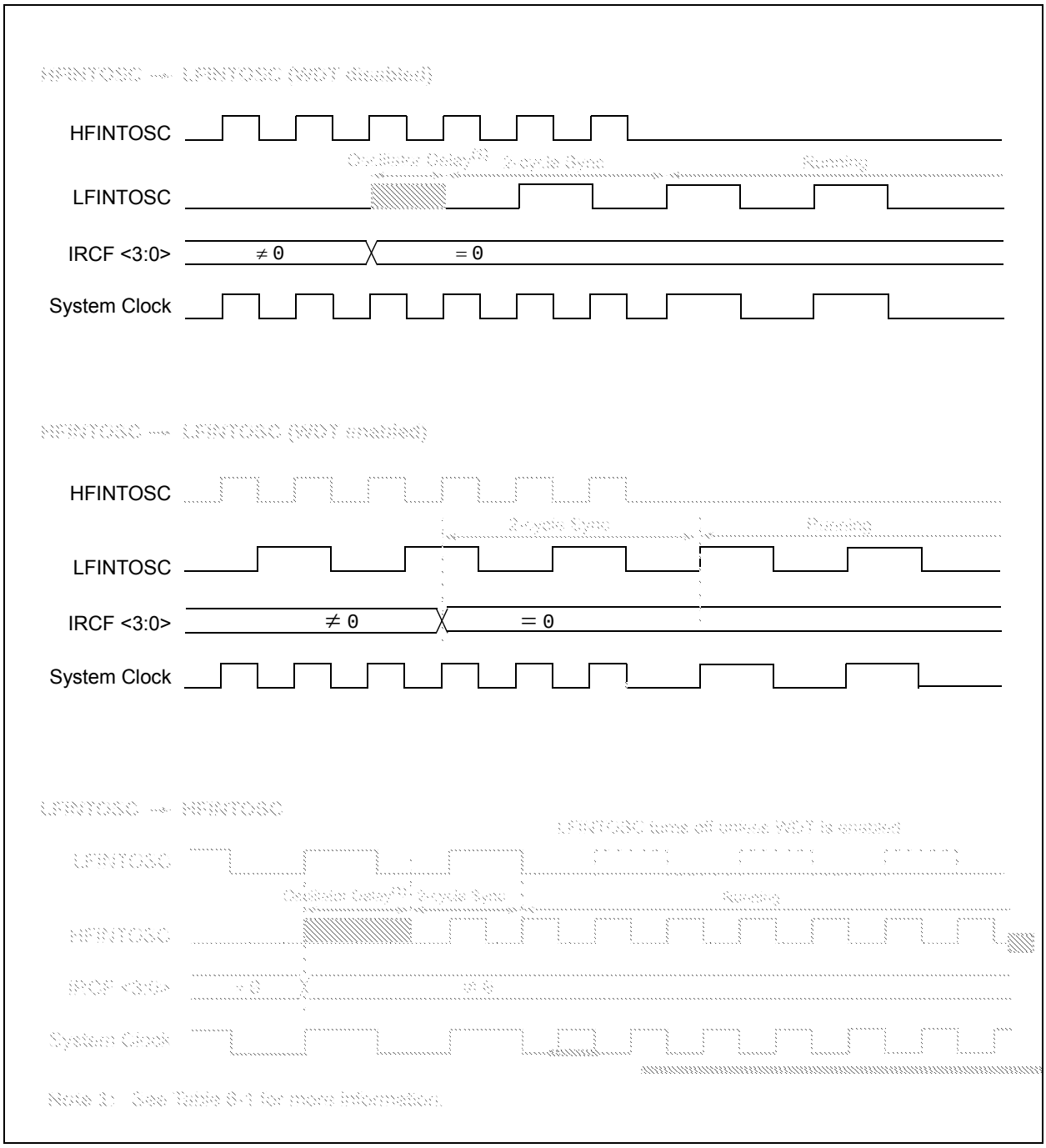


TABLE 6-1: OSCILLATOR SWITCHING DELAYS

Switch From	Switch To	Oscillator Delay
Any clock source	LFINTOSC	1 cycle of each clock source
	HFINTOSC	2 μs (approx.)
	ECH, ECM, ECL	2 cycles
	Secondary Oscillator	1024 Secondary Oscillator Cycles

6.3 Clock Switching

The system clock source can be switched between external and internal clock sources via software using the System Clock Select (SCS) bits of the OSCCON register. The following clock sources can be selected using the SCS bits:

- Default system oscillator determined by FOSC bits in Configuration Word 1
- Secondary oscillator 32 kHz crystal
- Internal Oscillator Block (INTOSC)

6.3.1 SYSTEM CLOCK SELECT (SCS) BITS

The System Clock Select (SCS) bits of the OSCCON register selects the system clock source that is used for the CPU and peripherals.

- When the SCS bits of the OSCCON register = `00`, the system clock source is determined by value of the FOSC<1:0> bits in the Configuration Word 1.
- When the SCS bits of the OSCCON register = `01`, the system clock source is the secondary oscillator.
- When the SCS bits of the OSCCON register = `1x`, the system clock source is chosen by the internal oscillator frequency selected by the IRCF<3:0> bits of the OSCCON register. After a Reset, the SCS bits of the OSCCON register are always cleared.

When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 6-2.

6.3.2 OSCILLATOR START-UP TIME-OUT STATUS (OSTS) BIT

The Oscillator Start-up Time-out Status (OSTS) bit of the OSCSTAT register indicates whether the system clock is running from the external clock source, as defined by the FOSC<1:0> bits in the Configuration Word 1, or from the internal clock source.

6.3.3 SECONDARY OSCILLATOR

The secondary oscillator is a separate crystal oscillator associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1OSI and T1CKI/T1OSO device pins.

The secondary oscillator is enabled using the T1OSCEN control bit in the T1CON register. See **Section 17.0 “Timer1 Module with Gate Control”** for more information about the Timer1 peripheral.

6.3.4 SECONDARY OSCILLATOR READY (T1OSCR) BIT

The user must ensure that the secondary oscillator is ready to be used before it is selected as a system clock source. The Secondary Oscillator Ready (T1OSCR) bit of the OSCSTAT register indicates whether the secondary oscillator is ready to be used. After the T1OSCR bit is set, the SCS bits can be configured to select the secondary oscillator.

6.4 Oscillator Control Registers

REGISTER 6-1: OSCCON: OSCILLATOR CONTROL REGISTER

U-0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
—	IRCF<3:0>				—	SCS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-3 **IRCF<3:0>:** Internal Oscillator Frequency Select bits
000x = 31 kHz LF
001x = 31.25 kHz
0100 = 62.5 kHz
0101 = 125 kHz
0110 = 250 kHz
0111 = 500 kHz (default upon Reset)
1000 = 125 kHz(1)
1001 = 250 kHz(1)
1010 = 500 kHz(1)
1011 = 1 MHz
1100 = 2 MHz
1101 = 4 MHz
1110 = 8 MHz
1111 = 16 MHz

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **SCS<1:0>:** System Clock Select bits
1x = Internal oscillator block
01 = Secondary oscillator
00 = Clock determined by FOSC<1:0> in Configuration Word 1.

Note 1: Duplicate frequency derived from HFINTOSC.

7.6.3 PIE2 REGISTER

The PIE2 register contains the interrupt enable bits, as shown in Register 7-3.

Note: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

REGISTER 7-3: PIE2: PERIPHERAL INTERRUPT ENABLE REGISTER 2

U-0	U-0	U-0	U-0	U-0	R/W-0/0	U-0	U-0
—	—	—	—	—	LCDIE	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **LCDIE:** LCD Module Interrupt Enable bit
1 = Enables the LCD module interrupt
0 = Disables the LCD module interrupt

bit 1-0 **Unimplemented:** Read as ‘0’

10.4 User ID, Device ID and Configuration Word Access

Instead of accessing program memory, the User ID's, Device ID/Revision ID and Configuration Words can be accessed when CFGS = 1 in the PMCON1 register. This is the region that would be pointed to by PC<15> = 1, but not all addresses are accessible. Different access may exist for reads and writes. Refer to Table 10-2.

When read access is initiated on an address outside the parameters listed in Table 10-2, the PMDATH:PMDATL register pair is cleared, reading back '0's.

TABLE 10-2: USER ID, DEVICE ID AND CONFIGURATION WORD ACCESS (CFGS = 1)

Address	Function	Read Access	Write Access
8000h-8003h	User IDs	Yes	Yes
8006h	Device ID/Revision ID	Yes	No
8007h-8008h	Configuration Words 1 and 2	Yes	No

EXAMPLE 10-4: CONFIGURATION WORD AND DEVICE ID ACCESS

```
* This code block will read 1 word of program memory at the memory address:
*   PROG_ADDR_LO (must be 00h-08h) data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select correct Bank
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    CLRF     PMADRH           ; Clear MSB of address

    BSF      PMCON1,CFGS      ; Select Configuration Space
    BCF      INTCON,GIE       ; Disable interrupts
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Executed (See Figure 10-2)
    NOP                       ; Ignored (See Figure 10-2)
    BSF      INTCON,GIE       ; Restore interrupts

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

REGISTER 10-6: PMCON2: PROGRAM MEMORY CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
Program Memory Control Register 2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **Flash Memory Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the PMCON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes.

TABLE 10-3: SUMMARY OF REGISTERS ASSOCIATED WITH FLASH PROGRAM MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
PMCON1	—(1)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	86
PMCON2	Program Memory Control Register 2								87
PMADRL	PMADRL<7:0>								85
PMADRH	—(1)	PMADRH<6:0>							85
PMDATL	PMDATL<7:0>								85
PMDATH	—	—	PMDATH<5:0>						85
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	60

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Flash Program Memory module.

Note 1: Unimplemented, read as '1'.

TABLE 10-4: SUMMARY OF CONFIGURATION WORD WITH FLASH PROGRAM MEMORY

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		—	34
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		—	FOSC<1:0>		
CONFIG2	13:8	—	—	LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	—	35
	7:0	—	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by clock sources.

REGISTER 11-5: PORTB: PORTB REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **RB<7:0>**: PORTB General Purpose I/O Pin bits(1)
1 = Port pin is ≥ VIH
0 = Port pin is ≤ VIL

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

REGISTER 11-6: TRISB: PORTB TRI-STATE REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **TRISB<7:0>:** PORTB Tri-State Control bits
1 = PORTB pin configured as an input (tri-stated)
0 = PORTB pin configured as an output

REGISTER 11-7: LATB: PORTB DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **LATB<7:0>**: PORTB Output Latch Value bits(1)

Note 1: Writes to PORTB are actually written to corresponding LATB register. Reads from PORTB register is return of actual I/O pin values.

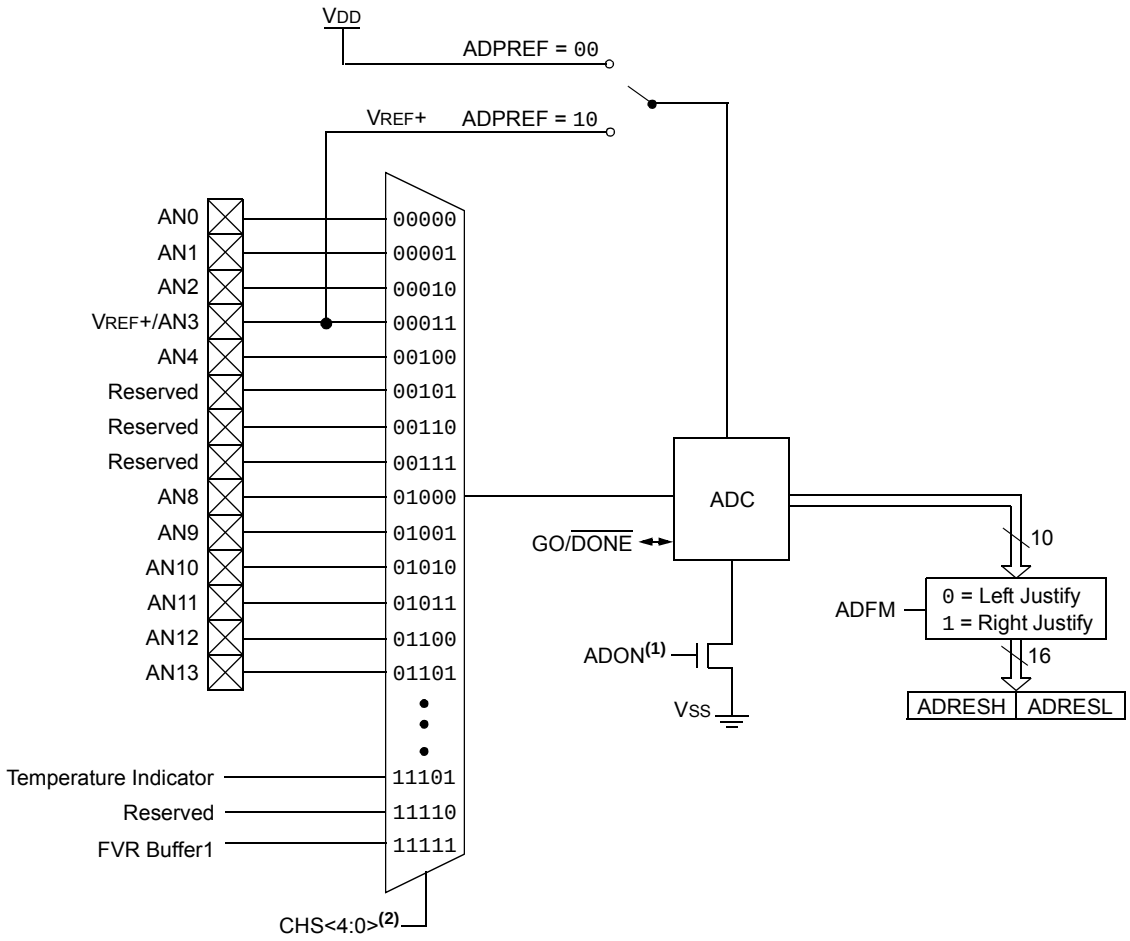
15.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 15-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 15-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.

2: See ADCON0 register (Example 15-1) for detailed analog channel selection per device.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 11.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are up to 11 channel selections available:

- AN<13:0> pins
- Temperature Indicator
- FVR (Fixed Voltage Reference) Output

Refer to **Section 13.0 "Fixed Voltage Reference (FVR)"** and **Section 14.0 "Temperature Indicator Module"** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 15.2 "ADC Operation"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provides control of the positive voltage reference. The positive voltage reference can be:

- V_{REF}+ pin
- V_{DD}

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- F_{OSC}/2
- F_{OSC}/4
- F_{OSC}/8
- F_{OSC}/16
- F_{OSC}/32
- F_{OSC}/64
- F_{RC} (dedicated internal oscillator)

The time to complete one bit conversion is defined as T_{AD}. One full 10-bit conversion requires 11.5 T_{AD} periods as shown in Figure 15-2.

For correct conversion, the appropriate T_{AD} specification must be met. Refer to the A/D conversion requirements in **Section 21.0 "Electrical Specifications"** for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the F_{RC}, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

TABLE 15-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})				
ADC Clock Source	ADCS<2:0>	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz
F_{OSC}/2	000	100 ns(2)	125 ns(2)	250 ns(2)	500 ns(2)	2.0 μs
F_{OSC}/4	100	200 ns(2)	250 ns(2)	500 ns(2)	1.0 μs	4.0 μs
F_{OSC}/8	001	400 ns(2)	0.5 μs(2)	1.0 μs	2.0 μs	8.0 μs(3)
F_{OSC}/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs(3)
F_{OSC}/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs(3)	32.0 μs(3)
F_{OSC}/64	110	3.2 μs	4.0 μs	8.0 μs(3)	16.0 μs(3)	64.0 μs(3)
F_{RC}	x11	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)

Legend: Shaded cells are outside of recommended range.

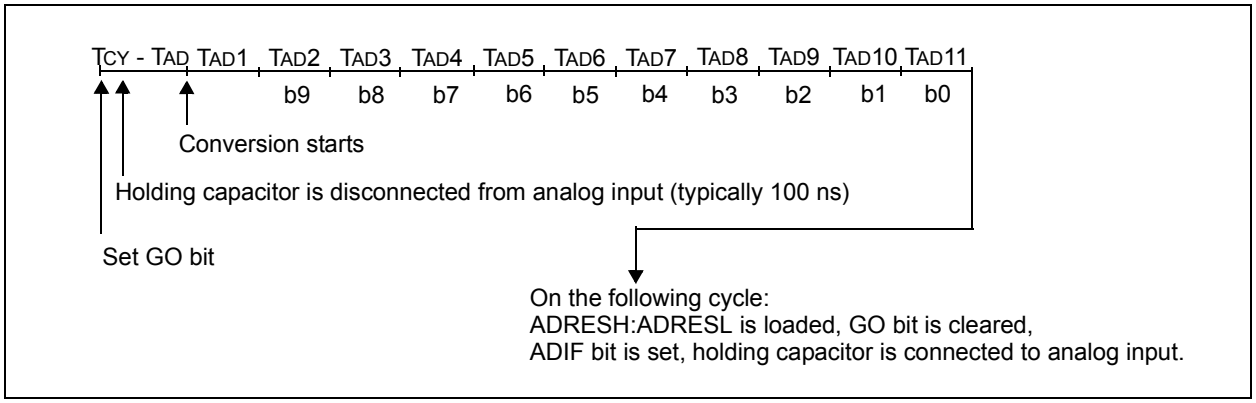
Note 1: The F_{RC} source has a typical T_{AD} time of 1.6 μs for V_{DD}.

2: These values violate the minimum required T_{AD} time.

3: For faster conversion times, the selection of another clock source is recommended.

4: The ADC clock period (T_{AD}) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock F_{OSC}. However, the F_{RC} clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 15-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



17.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4 or 8 divisions of the clock input. The T1CKPS bits of the T1CON register control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

17.4 Timer1 Oscillator

A dedicated low-power 32.768 kHz oscillator circuit is built-in between pins T1OSI (input) and T1OSO. This internal circuit is to be used in conjunction with an external 32.768 kHz crystal.

The oscillator circuit is enabled by setting the T1OSCEN bit of the T1CON register. The oscillator will continue to run during Sleep.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to enabling Timer1.

17.5 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ of the T1CON register is set, the external clock input is not synchronized. The timer increments asynchronously to the internal phase clocks. If the external clock source is selected then the timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (see **Section 17.5.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	When switching from synchronous to asynchronous operation, it is possible to skip an increment. When switching from asynchronous to synchronous operation, it is possible to produce an additional increment.

17.5.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the TMR1H:TMR1L register pair.

17.6 Timer1 Gate

Timer1 can be configured to count freely or the count can be enabled and disabled using Timer1 gate circuitry. This is also referred to as Timer1 Gate Enable.

Timer1 gate can also be driven by multiple selectable sources.

17.6.1 TIMER1 GATE ENABLE

The Timer1 Gate Enable mode is enabled by setting the TMR1GE bit of the T1GCON register. The polarity of the Timer1 Gate Enable mode is configured using the T1GPOL bit of the T1GCON register.

When Timer1 Gate Enable mode is enabled, Timer1 will increment on the rising edge of the Timer1 clock source. When Timer1 Gate Enable mode is disabled, no incrementing will occur and Timer1 will hold the current count. See Figure 17-3 for timing details.

TABLE 17-3: TIMER1 GATE ENABLE SELECTIONS

T1CLK	T1GPOL	T1G	Timer1 Operation
↑	0	0	Counts
↑	0	1	Holds Count
↑	1	0	Holds Count
↑	1	1	Counts

17.6.2 TIMER1 GATE SOURCE SELECTION

The Timer1 gate source can be selected from one of four different sources. Source selection is controlled by the T1GSS bits of the T1GCON register. The polarity for each available source is also selectable. Polarity selection is controlled by the T1GPOL bit of the T1GCON register.

TABLE 17-4: TIMER1 GATE SOURCES

T1GSS	Timer1 Gate Source
00	Timer1 Gate Pin
01	Overflow of Timer0 (TMR0 increments from FFh to 00h)

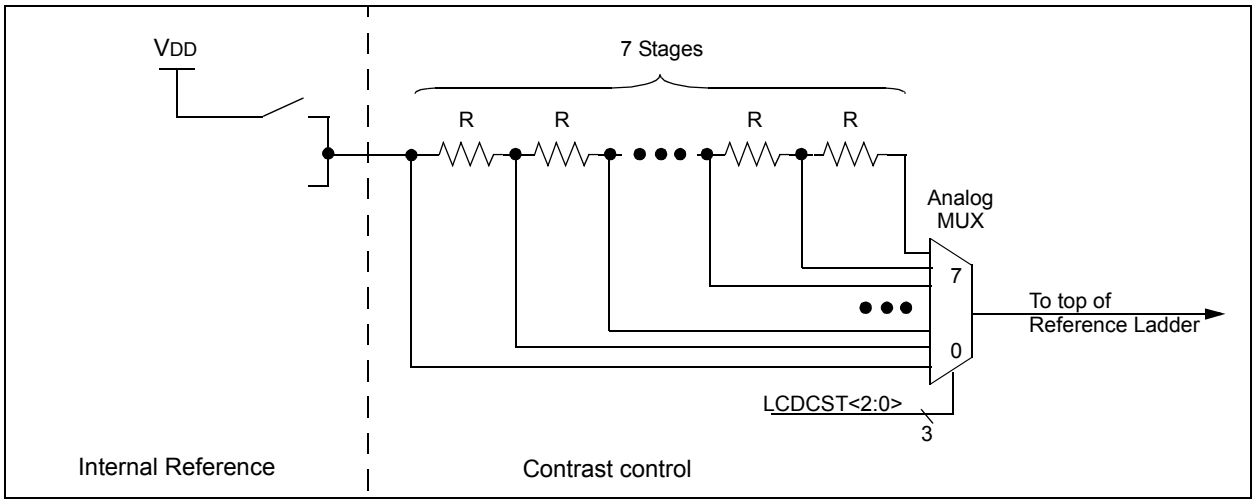
18.4.4 CONTRAST CONTROL

The LCD contrast control circuit consists of a 7-tap resistor ladder, controlled by the LCDCST bits. Refer to Figure 18-7.

The contrast control circuit is used to decrease the output voltage of the signal source by a total of approximately 10%, when LCDCST = 111.

Whenever the LCD module is inactive (LCDA = 0), the contrast control ladder will be turned off (open).

FIGURE 18-7: INTERNAL REFERENCE AND CONTRAST CONTROL BLOCK DIAGRAM



18.4.5 INTERNAL REFERENCE

Under firmware control, an internal reference for the LCD bias voltages can be enabled. When enabled, the source of this voltage can be VDD. When no internal reference is selected, the LCD contrast control circuit is disabled and LCD bias must be provided externally.

Whenever the LCD module is inactive (LCDA = 0), the internal reference will be turned off.

When the internal reference is enabled and the Fixed Voltage Reference is selected, the LCDIRI bit can be used to minimize power consumption by tying into the LCD reference ladder automatic power mode switching. When LCDIRI = 1 and the LCD reference ladder is in Power mode 'B', the LCD internal FVR buffer is disables.

Note:	The LCD module automatically turns on the Fixed Voltage Reference when needed.

18.4.6 VLCD<3:1> PINS

The VLCD<3:1> pins provide the ability for an external LCD bias network to be used instead of the internal ladder. Use of the VLCD<3:1> pins does not prevent use of the internal ladder. Each VLCD pin has an independent control in the LCDREF register (Register 18-3), allowing access to any or all of the LCD Bias signals. This architecture allows for maximum flexibility in different applications

For example, the VLCD<3:1> pins may be used to add capacitors to the internal reference ladder, increasing the drive capacity.

For applications where the internal contrast control is insufficient, the firmware can choose to only enable the VLCD3 pin, allowing an external contrast control circuit to use the internal reference divider.

18.5 LCD Multiplex Types

The LCD driver module can be configured into one of four multiplex types:

- Static (only COM0 is used)
- 1/2 multiplex (COM<1:0> are used)
- 1/3 multiplex (COM<2:0> are used)
- 1/4 multiplex (COM<3:0> are used)

The LMUX<1:0> bit setting of the LCDCON register decides which of the LCD common pins are used (see Table 18-4 for details).

If the pin is a digital I/O, the corresponding TRIS bit controls the data direction. If the pin is a COM drive, then the TRIS setting of that pin is overridden.

TABLE 18-4: COMMON PIN USAGE

Multiplex	LMUX <1:0>	COM3	COM2	COM1	COM1
Static	00	Unused	Unused	Unused	Active
1/2	01	Unused	Unused	Active	Active
1/3	10	Unused	Active	Active	Active
1/4	11	Active	Active	Active	Active

18.6 Segment Enables

The LCDSEn registers are used to select the pin function for each segment pin. The selection allows each pin to operate as either an LCD segment driver or as one of the pin's alternate functions. To configure the pin as a segment pin, the corresponding bits in the LCDSEn registers must be set to '1'.

If the pin is a digital I/O, the corresponding TRIS bit controls the data direction. Any bit set in the LCDSEn registers overrides any bit settings in the corresponding TRIS register.

Note:	On a Power-on Reset, these pins are configured as normal I/O, not LCD pins.

18.7 Pixel Control

The LCDDATAx registers contain bits which define the state of each pixel. Each bit defines one unique pixel.

Register 18-6 shows the correlation of each bit in the LCDDATAx registers to the respective common and segment signals.

Any LCD pixel location not being used for display can be used as general purpose RAM.

18.8 LCD Frame Frequency

The rate at which the COM and SEG outputs change is called the LCD frame frequency.

TABLE 18-5: FRAME FREQUENCY FORMULAS

Multiplex	Frame Frequency(2) =
Static	Clock source(1)/(4 x (LCD Prescaler) x 32 x 1))
1/2	Clock source(1)/(2 x (LCD Prescaler) x 32 x 2))
1/3	Clock source(1)/(1 x (LCD Prescaler) x 32 x 3))
1/4	Clock source(1)/(1 x (LCD Prescaler) x 32 x 4))

Note 1: Clock source is FOSC/256, T1OSC or LFINTOSC.

2: See Figure 18-2.

TABLE 18-6: APPROXIMATE FRAME FREQUENCY (IN Hz) USING FOSC @ 8 MHz, TIMER1 @ 32.768 kHz OR LFINTOSC

LP<3:0>	Static	1/2	1/3	1/4
2	122	122	162	122
3	81	81	108	81
4	61	61	81	61
5	49	49	65	49
6	41	41	54	41
7	35	35	47	35

TABLE 21-2: SUPPLY CURRENT (I_{DD})(1,2)

PIC16LF1902/3			Standard Operating Conditions (unless otherwise stated)				
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D010		—	58	75	µA	1.8	F_{OSC} = 1 MHz EC Oscillator mode High-Power mode
		—	115	140	µA	3.0	
		—	133	176	µA	3.6	
D011		—	130	200	µA	1.8	F_{OSC} = 4 MHz EC Oscillator mode High-Power mode
		—	245	300	µA	3.0	
		—	290	350	µA	3.6	
D012		—	218	275	µA	1.8	F_{OSC} = 500 kHz HFINTOSC mode
		—	283	375	µA	3.0	
		—	314	395	µA	3.6	
D013		—	233	325	µA	1.8	F_{OSC} = 1 MHz HFINTOSC mode
		—	309	425	µA	3.0	
		—	347	475	µA	3.6	
D014		—	305	360	µA	1.8	F_{OSC} = 4 MHz HFINTOSC mode
		—	433	520	µA	3.0	
		—	500	600	µA	3.6	
D015		—	395	480	µA	1.8	F_{OSC} = 8 MHz HFINTOSC mode
		—	600	720	µA	3.0	
		—	700	850	µA	3.6	
D016		—	567	670	µA	1.8	F_{OSC} = 16 MHz HFINTOSC mode
		—	915	1100	µA	3.0	
		—	1087	1300	µA	3.6	
D017		—	2.7	7.2	µA	1.8	F_{OSC} = 31 kHz LFINTOSC mode -40°C ≤ T_A ≤ +125°C
		—	4.5	9.7	µA	3.0	
		—	5.2	12.0	µA	3.6	
D017A		—	2.7	6.5	µA	1.8	F_{OSC} = 31 kHz LFINTOSC mode -40°C ≤ T_A ≤ +85°C
		—	4.5	9.0	µA	3.0	
		—	5.2	11.0	µA	3.6	
D018		—	2.4	6.7	µA	1.8	F_{OSC} = 32 kHz EC Oscillator mode, Low-Power mode -40°C ≤ T_A ≤ +125°C
		—	4.2	9.2	µA	3.0	
		—	4.8	11.5	µA	3.6	
D018A		—	2.4	6.0	µA	1.8	F_{OSC} = 32 kHz EC Oscillator mode, Low-Power mode -40°C ≤ T_A ≤ +85°C
		—	4.2	8.5	µA	3.0	
		—	4.8	10.5	µA	3.6	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: FVR and BOR are disabled.

TABLE 21-4: I/O PORTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
	V_{IL}	**Input Low Voltage**					
		I/O PORT:					
D032		with TTL buffer	—	—	0.15 V_{DD}	V	1.8V ≤ V_{DD} ≤ 3.6V
D033		with Schmitt Trigger buffer	—	—	0.2 V_{DD}	V	1.8V ≤ V_{DD} ≤ 3.6V
D034		$\overline{MCLR}$, OSC1	—	—	0.2 V_{DD}	V	
	V_{IH}	**Input High Voltage**					
		I/O ports:					
D040		with TTL buffer	0.25 V_{DD} + 0.8	—	—	V	1.8V ≤ V_{DD} ≤ 3.6V
D041		with Schmitt Trigger buffer	0.8 V_{DD}	—	—	V	1.8V ≤ V_{DD} ≤ 3.6V
D042		$\overline{MCLR}$	0.8 V_{DD}	—	—	V	
	I_{IL}	**Input Leakage Current(2)**					
D060		I/O ports	—	± 5	± 125	nA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, Pin at high-impedance @ 85°C
				± 5	± 1000	nA	125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	V_{SS} ≤ V_{PIN} ≤ V_{DD} @ 85°C
	I_{PUR}	**Weak Pull-up Current**					
D070*			25	100	200	µA	V_{DD} = 3.3V, V_{PIN} = V_{SS}
	V_{OL}	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	I_{OL} = 6mA, V_{DD} = 3.3V I_{OL} = 1.8mA, V_{DD} = 1.8V
	V_{OH}	**Output High Voltage**					
D090		I/O ports	V_{DD} - 0.7	—	—	V	I_{OH} = 3mA, V_{DD} = 3.3V I_{OH} = 1mA, V_{DD} = 1.8V
		Capacitive Loading Specs on Output Pins					
D101*	C_{IO}	All I/O pins	—	—	50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Negative current is defined as current sourced by the pin.

TABLE 21-5: MEMORY PROGRAMMING REQUIREMENTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Program Memory High Voltage Programming Specifications					
D110	VIHH	Voltage on $\overline{MCLR}$/VPP/RE3 pin	8.0	—	9.0	V	**(Note 2)**
D111	IDDVPP	Programming/Erase Current on VPP, High Voltage Programming	—	—	10	mA	
D112		VDD for Bulk Erase	2.7	—	VDD max.	V	
D113	VPEW	VDD for Write or Row Erase	VDD min.	—	VDD max.	V	
D114	IPPPGM	Programming/Erase Current on VPP, Low Voltage Programming	—	—	1.0	mA	
D115	IDDPGM	Programming/Erase Current on VDD, High or Low Voltage Programming	—		5.0	mA	
		Program Flash Memory					
D121	EP	Cell Endurance	1K	10K	—	E/W	-40°C to +85°C (**Note 1**)
D122	VPR	VDD for Read	VDD min.	—	VDD max.	V	
D123	TIW	Self-timed Write Cycle Time	—	2	2.5	ms	
D124	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Self-write and Block Erase.

2: Required only if single-supply programming is disabled.

TABLE 21-6: THERMAL CONSIDERATIONS

Standard Operating Conditions (unless otherwise stated)					
Param. No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θJA	Thermal Resistance Junction to Ambient	60	°C/W	28-pin SPDIP package
			80	°C/W	28-pin SOIC package
			90	°C/W	28-pin SSOP package
			27.5	°C/W	28-pin UQFN 4x4mm package
TH02	θJC	Thermal Resistance Junction to Case	31.4	°C/W	28-pin SPDIP package
			24	°C/W	28-pin SOIC package
			24	°C/W	28-pin SSOP package
			24	°C/W	28-pin UQFN 4x4mm package
TH03	TJMAX	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = PINTERNAL + PI/O
TH05	PINTERNAL	Internal Power Dissipation	—	W	PINTERNAL = IDD x VDD(1)
TH06	PI/O	I/O Power Dissipation	—	W	PI/O = Σ (IOL * VOL) + Σ (IOH * (VDD - VOH))
TH07	PDER	Derated Power	—	W	PDER = PDMAX (TJ - TA)/θJA(2)

Note 1: IDD is current to run the chip alone without driving any load on the output pins.

2: TA = Ambient Temperature

3: TJ = Junction Temperature

23.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

23.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

23.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

23.5 MPLAB Assembler, Linker and Librarian for Various Device Families

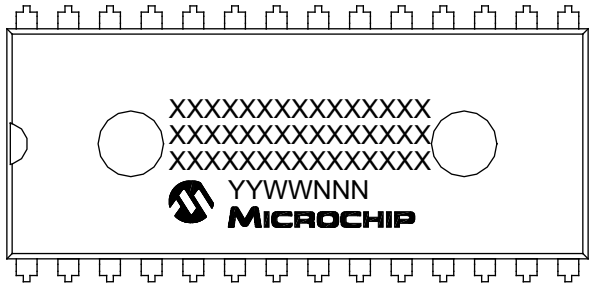
MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

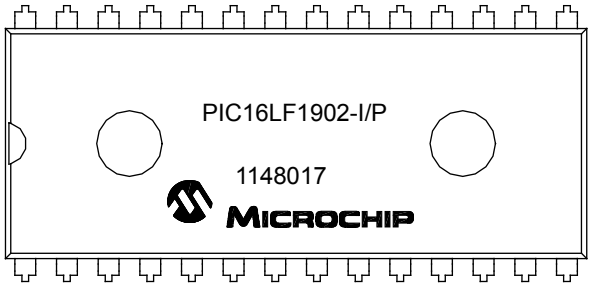
24.0 PACKAGING INFORMATION

24.1 Package Marking Information

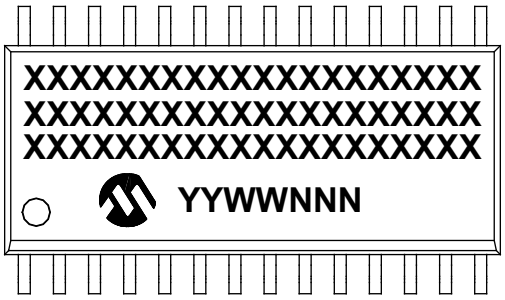
28-Lead PDIP (600 mil)



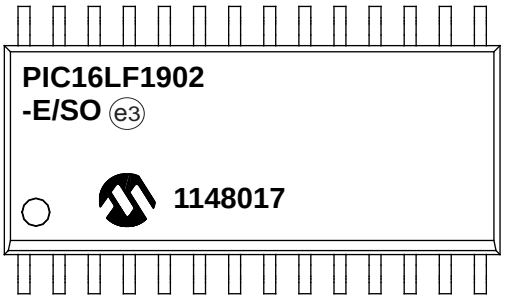
Example



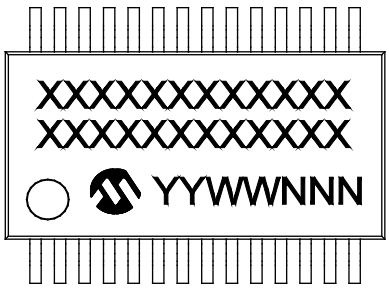
28-Lead SOIC (7.50 mm)



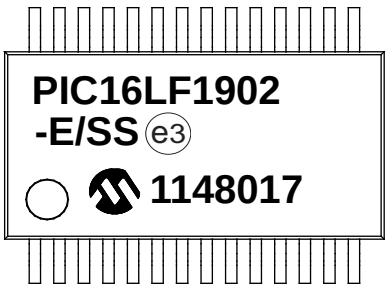
Example



28-Lead SSOP (5.30 mm)



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC® designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.